

- Was the machine used for lapping (NO grinding!)?

For lapping

- What material was lapped?

Silicon

Upper plate:30×30 mm grid,groove width 2 mm,groove depth 18mm

Lower plate:40×40 mm grid,groove width 2 mm,groove depth 18 mm

- What kind of drives are in the machine?

Mitsubishi drives.

- Is the operational interface in English or other languages available?

It's English and can be Chinese

- What condition have the working tables, remaining height etc.

Upper plate:30×30 mm grid,groove width 2 mm,groove depth 17.5mm

Lower plate:40×40 mm grid,groove width 2 mm,groove depth 17.5mm

- What kind of grooves are in the working table

Upper plate:30×30 mm grid,groove width 2 mm,groove depth 17.5mm

Lower plate:40×40 mm grid,groove width 2 mm,groove depth 17.5mm

- Are there supplemental machines like centrifuge, filter for slurry etc., slurry bucket & pump?slurry bucket & pump included

- Frequency / Voltage

50HZ/220V